



Datasheet

BL54L15, BL54L10 Series

Version 1.8

Revision History

Version	Date	Notes	Contributor(s)	Approver
0.1	10 June 2024	Initial PRELIMINARY release.	Raj Khatri	Jonathan Kaye
0.2	2 Oct 2024	Updated pin list names and notes below table1. Added section External Antenna Integration with BL54L15/BL54L10 MHF4 variant (453-00044/453-00226) Added section on Programmability.	Raj Khatri	Jonathan Kaye
0.3	24 Oct 2024	Removed Medium voltage mode (VDDM_nRF) from Specification Summary table and updated Normal voltage mode (VDD_nRF) operating range from 1.7V-2.6V to 1.7V-3.6V. Updated Block Diagram and Pin-out for 39 connection pins. Updated SCH symbol to remove pin40. Updated pin list in Table 1 (removed pin 40 VDDM_nRF). Updated BL54L15/ BL54L10 Power Supply Updated Table 4 external antenna Mag Layers EDA-8709-2G4C1-B27-CY antenna gain from 2dBi to 2.32dBi.	Raj Khatri	Jonathan Kaye
0.4	6 Dec 2024	Updated maximum Tx power to +7 dBm.	Dave Drogowski	Jonathan Kaye
0.5	11 Dec 2024	Updated sensitivity value Added trace antenna performance	Louis Chang	Jonathan Kaye
0.6	16 Dec 2024	Updated maximum Tx power to +6 dBm.	Louis Chang	Jonathan Kaye
1.0	16 Dec 2024	Initial release	Dave Drogowski	Jonathan Kaye
1.1	19 Dec 2024	Updated maximum Tx power to +7 dBm.	Louis Chang	Jonathan Kaye
1.2	13 Jan 2025	Updated title of 7.4 Updated some typo	Louis Chang	Jonathan Kaye
1.3	21 Feb. 2025	Change (VDD_nRF) operating range from 1.7V-3.6V to 1.7V-3.5V. Add VDD_nRF supply voltage (1.7V-3.3V) under extended operating Temperature (85 to 105C) Update Absolute maximum ratings of VDD_nRF (-0.3V-3.6V)	Louis Chang	Jonathan Kaye
1.4	25 Feb. 2025	Update Minimum Transmit Power Setting to -40dBm Update Active Modes Peak Current	Louis Chang	Jonathan Kaye
1.5	27 Feb. 2025	Update 32MHz crystal oscillator internal capacitor setting value Update 32.768KHz crystal oscillator internal capacitor setting value Update NFC antenna pin current value	Louis Chang	Jonathan Kaye
1.6	3 Mar. 2025	Update Idle mode and off mode current BL54L10 Antenna performance shares with BL54L15	Louis Chang	Jonathan Kaye
1.7	10 Mar. 25	Update 2.4GHz Radiated Performance Update flash specs in Absolute Maximum Ratings	Louis Chang	Jonathan Kaye
1.8	18 Mar. 25	Update power consumption in 2.1	Louis Chang	Jonathan Kaye

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1 Overview and Key Features

Experience a new pinnacle of performance, efficiency, and security with our new BL54L15 and BL54L10 series, built on Nordic Semiconductor's powerful **nRF54L QFN** silicon. Elevating what you know and love from the nRF52 series, this next generation redefines Bluetooth LE and 802.15.4 solutions. Unleashing enhanced processing power, expanded memory, and innovative peripherals, the BL54L15 is the ultimate choice for low power connectivity.

Powered by **Nordic's nRF54L15 and nRF54L10 SoC**, our compact BL54L15 and BL54L10 modules deliver secure and robust Bluetooth LE and 802.15.4 with flexible programming via Nordic's nRF Connect SDK or Ezurio Canvas Software Suite.

Featuring a **128MHz ARM Cortex M33** and **128MHz RISC-V coprocessor**, supported by 1.5 MB non-volatile memory and 256 KB RAM for BL54L15, 1.0 MB non-volatile memory and 192 KB RAM for BL54L10, the BL54L15 and BL54L10 modules offer double the processing power (vs prior BL654 – nRF52840). The BL54L15 / L10 series brings out all nRF54L15/ L10 hardware features and capabilities including up to **+7 dBm** transmit power, **1.7V – 3.5V** supply considerations, and **NFC A-Tag** implementation.

It's further enhanced with state-of-the-art security and is designed for PSA Certified level 3 and supports services such as Secure Boot, Secure Firmware Update, Secure Storage plus protection from physical attacks.

Note: BL54L15/ BL54L10 hardware provides all functionality of the nRF54L15/ nRF54L10 chipset used in the module design. This is a hardware datasheet only – it does not cover the software aspects of the BL54L15 and BL54L10. This is to acknowledge that information in this datasheet is referenced from the nRF54L15/ nRF54L10 datasheet.



1.1 Features and Benefits

- **Nordic nRF54L15/ nRF54L10** – 6x6 mm QFN48 with 31 GPIOs utilized.
- **Multi-protocol support:** Bluetooth LE, 802.15.4 (Thread & Matter)
- **Cortex M33** processor core: 128 MHz ARM Cortex M33
- **RISC-V** co-processor core: 128 MHz VPR
- **Memory:** 1.5MB non-volatile memory, 256 KB RAM for BL54L15
1.0MB non-volatile memory, 192 KB RAM for BL54L10
- **High Speed Peripherals:** - HS-SPI/UART, software defined peripherals on 128 MHz VPR, GPIO – 1x 64 MHz Port, 1.7 – 3.5V, 11 GPIOs
- **Low Leakage Peripherals:** 2x QDEC, 7x Timer, Global RTC, 2x WDT, NFC A-Tag, TEMP, I2S, COMP, 3x PWM, LPCOMP, 14-bit 8CH ADC, 5x TWI/SPI/UART, GPIO (2x 16 MHz Port (P0, P1), 20 GPIO's, 1.7-3.5V, 31 GPIO)
- **Antenna choice** – integrated pre-certified **PCB Trace antenna** or external antenna support via **MHF4 connector**
- **Ultra-small footprint** (14 mm x 10 mm x 1.6 mm)
- **Extended Industrial Temperature Rating** (-40° to +105 °C)
- **Bluetooth LE:** Channel Sounding, LE 2M, LE Coded, LE Secure Connections & more
- **Qualified against Bluetooth Core 6.0**
- **Firmware Over the Air (FOTA)** via MCUboot and nRF Connect SDK
- **Hostless operation** – Multi Core MCU reduces BOM
- **Fully featured development kits** to jump start Bluetooth LE development
- **BL54L15 and BL54L10 are 100% drop in options, pin for pin**

1.2 Application Areas

- Building Automation
- Security
- Medical Peripherals
- Industrial Sensors

2 Specification

2.1 Specification Summary

Categories/Feature	Implementation										
Specification											
Bluetooth®	Bluetooth Core 6.0 - Channel Sounding - GATT client & GATT server – Any adopted/custom services - Central/Peripheral roles - Mesh networking - LE CODED - LE 2M - LE Secure Connections - Extended Advertising - LE Power Control - DTM Firmware (Test Modes)										
IEEE 802.15.4-2020 PHY	2405–2480 MHz IEEE 802.15.4-2006 radio transceiver, implementing IEEE 802.15.4-2006 compliant 250kbps, 2450MHz, O-QPSK PHY - Channels 11-26. Channel 11 2405MHz and CH26 2480MHz. - Clear channel assessment (CCA) - Energy detection (ED) scan - CRC generation										
Nordic proprietary 1Mbps, 2Mbps, 4Mbps modes radio	2402–2480 MHz Nordic proprietary 1Mbps and 2Mbps modes radio transceiver 1Mbps nRF proprietary mode (ideal transmitter) 2Mbps nRF proprietary mode (ideal transmitter) 4Mbps nRF proprietary mode (ideal transmitter)										
Frequency	2.402 - 2.480 GHz for BLE (CH0 to CH39) 2.405 - 2.480 GHz for IEEE 802.15.4-2006 PHY (CH11 to CH26)										
Raw Data Rates	1 Mbps BLE (over-the-air) 2 Mbps BLE (over-the-air) 125 kbps BLE (over-the-air) 500 kbps BLE (over-the-air) 250 kbps IEEE 802.15.4-2020 (over-the-air) Nordic proprietary 1Mbps, 2Mbps and 4Mbps modes (over-the-air)										
Maximum Transmit Power Setting	+7 dBm Conducted 453-00001, 453-00225 (Integrated antenna) (Exclude antenna gain) +7 dBm Conducted 453-00044, 453-00226 (External antenna) (Test at MHF4 connector)										
Minimum Transmit Power Setting	-40 dBm										
Receive Sensitivity ¹ (≤37byte packet for BLE)	<table> <tr> <td>BLE 1 Mbps (BER=1E-3)</td><td>-94 dBm typical</td></tr> <tr> <td>BLE 2 Mbps</td><td>-92 dBm typical</td></tr> <tr> <td>BLE 125 kbps</td><td>-102 dBm typical</td></tr> <tr> <td>BLE 500 kbps</td><td>-98 dBm typical</td></tr> <tr> <td>IEEE 802.15.4-2020 250kbps</td><td>TBD dBm typical</td></tr> </table>	BLE 1 Mbps (BER=1E-3)	-94 dBm typical	BLE 2 Mbps	-92 dBm typical	BLE 125 kbps	-102 dBm typical	BLE 500 kbps	-98 dBm typical	IEEE 802.15.4-2020 250kbps	TBD dBm typical
BLE 1 Mbps (BER=1E-3)	-94 dBm typical										
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BLE 125 kbps	-102 dBm typical										
BLE 500 kbps	-98 dBm typical										
IEEE 802.15.4-2020 250kbps	TBD dBm typical										
Link Budget (conducted)	<table> <tr> <td>101 dB</td><td>@ BLE 1 Mbps (TX power used is 7dBm)</td></tr> <tr> <td>109 dB</td><td>@ BLE 125 kbps (TX power used is 7dBm)</td></tr> </table>	101 dB	@ BLE 1 Mbps (TX power used is 7dBm)	109 dB	@ BLE 125 kbps (TX power used is 7dBm)						
101 dB	@ BLE 1 Mbps (TX power used is 7dBm)										
109 dB	@ BLE 125 kbps (TX power used is 7dBm)										
NFC											
NFC-Type A	Based on NFC forum specification: 13.56 MHz, Data rate 106 kbps, NFC Type2 and Type 4 emulation										

Note¹ Known Noise on channels 2432MHz and 2464MHz degrades receiver sensitivity, in which sensitivity are not within the typical value

Listen mode compliant	Modes of Operation: Disable, Sense, Activated Use Cases: Touch-to-Pair with NFC, NFC enabled Out-of-Band Pairing
Security	Designed for PSA Certified Level 3 with Secure Boot, Secure Firmware Update, and Secure Storage. Integrated tamper sensors detect attacks and take action, and cryptographic accelerators are hardened against side-channel attacks.

Host Interfaces and Peripherals	Application Core (High Performance)	Software defined peripheral Core (ultra-low power)
Total		31 x multifunction I/O lines
Two co-processors	Arm Cortex-M33 with DSP, FPU, TrustZone support. 1524KB non-volatile RRAM (BL54L15) 1022KB non-volatile RRAM (BL54L10) 256KB RAM (BL54L15) 192KB RAM (BL54L10) L1 cache 128MHz clock Uses voltage and clock frequency scaling	RISC-V CPU (VPR) fast lightweight peripheral processor (FLPR) dedicated for software defined peripherals 16MHz clock
GPIO		Up to 31 multifunction GPIO's
	64MHz 1.7-3.5V GPIO port P2.00-P2.10	16MHz 1.7-3.5V GPIO port P1.00-P1.14; P0.00-P0.04
ADC (14-bit)	14-bit 31.25KS/s with oversampling 12-bit 250KS/s 10-bit 2MS/s AIN0-AIN7 pins upto 8 programmable gain channels	
Global RTC (GRTC)		Implements full real time clock and calendar as shared system time. Can run in System OFF mode. Ultra low power, 1us resolution, 52bits wide, uses 16MHz clock, 32.76kHz when other power modes.
RTC		2x low power runs off LFCLK
High Speed SPI/UART	1 x	
SPI/UART/TWI		4x
PWM		3x 4channel PWM
I2S		1x I2S (Inter-IC sound interface)
PDM		1x PDM (Pulse code modulation interface) for digital microphones
TIMER		7x Timer (32bit)
QDEC		2x QDEC (Quadrature decoder)
COMP		1x COMP (comparator)
LPCOMP		1x LPCOMP (low power comparator)
TEMP		1x Temperature sensor Temperature range equal to operating temperature range
WDT		2x WDT (Watchdog timer)
NFC A-Tag		1x
Wakeup pins		20x
External optional		Not needed for normal radio operation.

Host Interfaces and Peripherals	Application Core (High Performance)	Software defined peripheral Core (ultra-low power)
32.768 kHz crystal		Optionally, connect +/-20ppm accuracy crystal for more accurate protocol timing. Fit associated load capacitor for crystal or use nRF54L15/nRF54L10 internal load capacitor, which is configurable as 4 pF to 18 pF in 0.5 pF steps on pins XL1, XL2.
Security	Designed for PSA Certified Level 3 with Secure Boot, Secure Firmware Update, and Secure Storage. Integrated tamper sensors detect attacks and take action, and cryptographic accelerators are hardened against side-channel attacks.	
Programmability	Via SWD (JTAG) 2 wire interface	
Options	Nordic nRFConnect SDK: Software/Support available from Nordic directly https://devzone.nordicsemi.com/ Canvas SW Suite: Software/ Support available from https://www.ezurio.com/canvas/software-suite	
FW upgrade	Via SWD (JTAG) 2 wire interface or UART	
Supply Voltage	Normal Voltage Mode (VDD_nRF): 1.7V-3.5V (Internal DCDC convertor or LDO)	
Power Consumption		
Active Modes Peak Current (for max Tx power +7dBm)– Radio only	30 mA peak Tx@ 1.8V, LE1M	
	25 mA peak Tx@ 1.8V, CW	
	17 mA peak Tx@ 3.3V, LE1M	
	14 mA peak Tx@ 3.3V, CW	
Active Modes Peak Current (for Tx power -40dBm) – Radio only	8 mA peak Tx @ 1.8V, LE1M	
	7 mA peak Tx @ 1.8V, CW	
	6.5 mA peak Tx @ 3.3V, LE1M	
	5 mA peak Tx @ 3.3V, CW	
Active Modes Average Current	Depends on many factors.	
Ultra-low Power Modes	System ON Idle	3 uA (System ON IDLE with GRTC (XOSC) and 256 KB RAM) 2.6uA(System ON IDLE with GRTC (XOSC) and 192 KB RAM)
	System OFF	0.6 uA
Antenna Options		
Internal	PCB Trace antenna – on-board (453-00001 variant for BL54L15, 453-00225 variant for BL54L10)	
External	Connection via on module IPEX MHF4 (453-00044 variant for BL54L15, 453-00226 variant for BL54L10)	
Physical		
Dimensions	14mm x 10mm x 1.6mm Pad Pitch – 0.75 mm Pad Type – Three rows of pads (LGA - Land Grid Array).	
Weight	<1 gram	
Environmental		
Operating	-40 °C to +105 °C	
Storage	-40 °C to +105 °C	
Miscellaneous		
Lead Free	Lead-free and RoHS compliant	
Warranty	One-Year Warranty	
Development Tools		
Development Kit	Development kit per module SKU (453-00001-K1 and 453-00044-K1 respectively, BL54L15 only) Utilise the above development kits for projects planned with BL54L10.	
Development Tools	Nordic nRFConnect - Android and iOS applications UART firmware upgrade Xbit Tools and utilities	
Bluetooth®	Full Bluetooth SIG Declaration ID	

已註解 [LC2R1]: use nRF54L15 datasheet value preliminarily

3 Hardware Specifications

3.1 Block Diagram and Pin-out

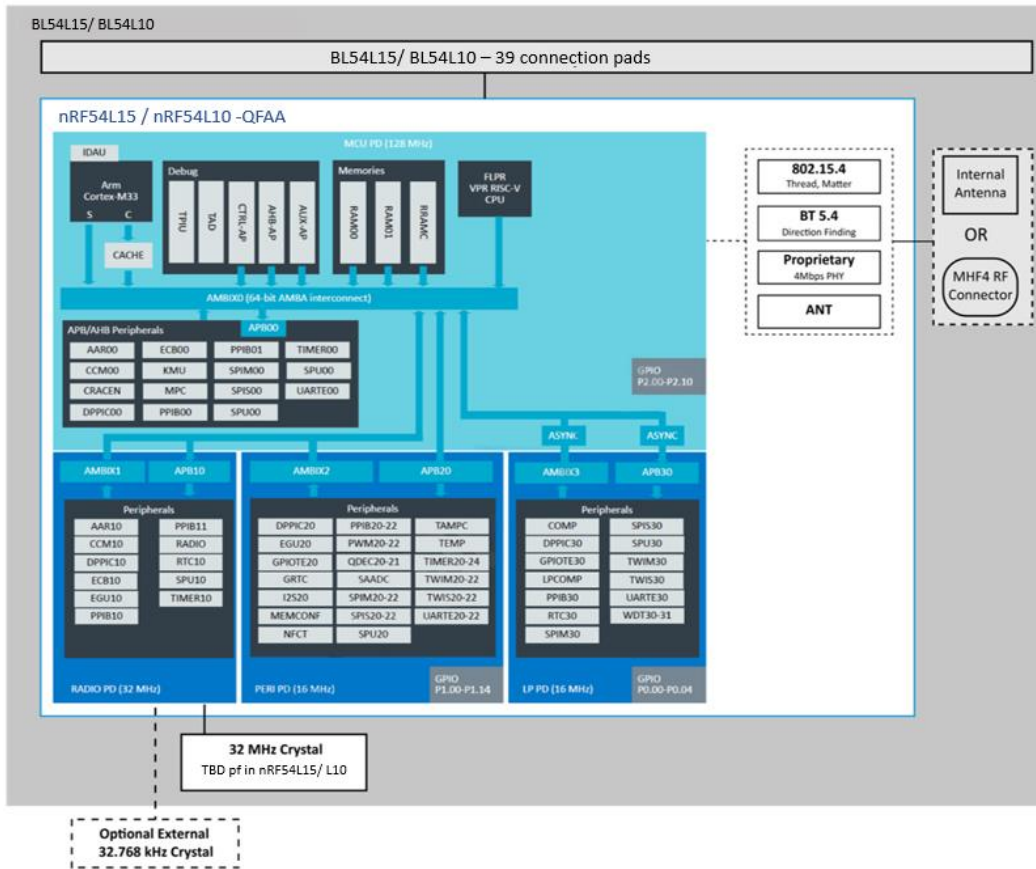


Figure 1: BL54L15/ BL54L10 HW block diagram

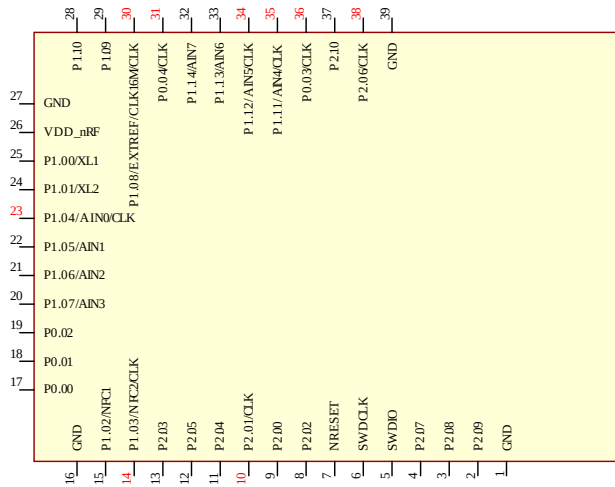


Figure 2: Top view - Schematic symbol for 453-00001/453-00225 BL54L15/L10 Module (Nordic nRF54L15/L10) - Integrated PCB Trace Antenna variant or 453-00044/453-00226 MHF4 RF connector variant

3.2 Pin Definitions

Table 1: Pin definitions

Pin #	Pin Name (red coloured pins for clock for interfaces, trace)	nRF54L15 nRF54L10 QFN48 Pin	nRF54L15/ nRF54L10 QFN48 Name	Description	Example usage
1	GND	-	VSS		
2	P2.09	20	P2.09/TRACEDATA[2]/SPI.SDI/SD O	General purpose I/O Trace data SPIM SDI SPIS SDI UARTE CTS	Trace SPIM00/SPIM21 SPIS00/SPIS21 UARTE00/UARTE21
3	P2.08	19	P2.08/TRACEDATA[1]/SPI.SDI/SD O	General purpose I/O Trace data SPIM SDO SPIS SDO UARTE TXD	Trace SPIM00/SPIM21 SPIS00/SPIS21 UARTE00/UARTE21
4	P2.07	18	P2.07/TRACEDATA[0]/SWO/SPI.D CX	General purpose I/O Trace data Serial wire output (SWO) SPIM DCX UARTE RXD	Trace Trace SPIM00/SPIM21 UARTE00/UARTE21
5	SWDIO	25	SWDIO	Serial Wire Debug IO for debug and programming	
6	SWDCLK	26	SWDCLK	Serial Wire Debug clock input for debug and programming	
7	NRESET	30	nRESET	Pin RESET with internal pull- up resistor (13k Ohms). System Reset (Active Low).	

Pin #	Pin Name (red coloured pins for clock for interfaces, trace)	nRF54L15 nRF54L10 QFN48 Pin	nRF54L15/ nRF54L10 QFN48 Name	Description	Example usage
8	P2.02	13	P2.02/SPI.SDI/SDO	General purpose I/O SPIM SDO SPIS SDO UARTE TXD QSPI D0 Serial wire output (SWO)	SPIM00/SPIM20 SPIS00/SPIS20 UARTE00/UARTE20 FLPR Trace
9	P2.00	11	P2.00/SPI.DCX	General purpose I/O SPIM DCX UARTE RXD QSPI D3	SPIM00/SPIM20 UARTE00/UARTE20 FLPR (QSPI)
10	P2.01/CLK	12	P2.01/SPI.SCK	General purpose I/O SPIM SCK SPIS SCK QSPI SCK	Clock pin SPIM00/SPIM20 SPIS00/SPIS20 FLPR
11	P2.04	15	P2.04/SPI.SDI/SDO	General purpose I/O SPIM SDI SPIS SDI UARTE CTS QSPI D1	SPIM00/SPIM20 SPIS00/SPIS20 UARTE00/UARTE20 FLPR
12	P2.05	16	P2.05/SPI.CS	General purpose I/O SPIM CS UARTE RTS QSPI CS	SPIM00/SPIM20 UARTE00/UARTE20 FLPR
13	P2.03	14	P2.03	General purpose I/O QSPI D2	FLPR
14	P1.03/NFC2/CLK	4	P1.03/NFC2	General purpose I/O Dedicated pin for NFC input	Clock pin
15	P1.02/NFC1	3	P1.02/NFC1	General purpose I/O Dedicated pin for NFC input	
16	GND				
17	P0.00	23	P0.00	General purpose I/O	
18	P0.01	24	P0.01	General purpose I/O	
19	P0.02	27	P0.02	General purpose I/O	
20	P1.07/AIN3	8	P1.07/AIN3/TAMPC	General purpose I/O TAMPC active shield 1 input Analog input	TAMPC
21	P1.06/AIN2	7	P1.06/AIN2/TAMPC	General purpose I/O TAMPC active shield 1 output Analog input	TAMPC
22	P1.05/AIN1	6	P1.05/AIN1/TAMPC	General purpose I/O TAMPC active shield 0 input RADIO DFEGPIO Analog input	TAMPC RADIO
23	P1.04/AIN0/CLK	5	P1.04/AIN0/TAMPC	General purpose I/O TAMPC active shield 0 output Analog input	Clock pin TAMPC
24	P1.01/XL2	2	P1.01/XL2	General purpose I/O	Ezurio Devkit: Optional 32.768kHz crystal pad XL2, XL1 and

Pin #	Pin Name (red coloured pins for clock for interfaces, trace)	nRF54L15 nRF54L10 QFN48 Pin	nRF54L15/ nRF54L10 QFN48 Name	Description	Example usage
				General purpose I/O Connection for 32.768kHz crystal	associated 9pF load capacitor inside nRF54L15 chipset.
25	P1.00/XL1	1	P1.00/XL1	General purpose I/O Connection for 32.768kHz crystal	Ezurio Devkit: Optional 32.768kHz crystal pad XL2, XL1 and associated 9pF load capacitor inside nRF54L15 chipset.
26	VDD_nRF	48	VDD	1.7V-3.5V input for Normal Voltage Mode where connect external supply to VDD_nRF(pin26). See 3.5 BL54L15/ BL54L10 Power Supply	
27	GND				
28	P1.10	38	P1.10/TAMPC	General purpose I/O TAMPC active shield 2 input RADIO DFEGPIO	TAMPC RADIO
29	P1.09	37	P1.09/TAMPC	General purpose I/O TAMPC active shield 2 output RADIO DFEGPIO	TAMPC RADIO
30	P1.08/EXTREF/CLK16M/CLK	9	P1.08/CLK16M/TAMPC	General purpose I/O GRTC HF clock output External reference for SAADC	Clock pin
31	P0.04/CLK	29	P0.04/GRTC_CLKOUT32K	General purpose I/O GRTC LF clock output	Clock pin GRTC
32	P1.14/AIN7	42	P1.14/AIN7	General purpose I/O RADIO DFEGPIO Analog input	RADIO
33	P1.13/AIN6	41	P1.13/AIN6	General purpose I/O RADIO DFEGPIO Analog input	RADIO
34	P1.12/AIN5/CLK	40	P1.12/AIN5	General purpose I/O TAMPC active shield 3 input RADIO DFEGPIO Analog input	Clock pin TAMPC RADIO
35	P1.11/AIN4/CLK	39	P1.11/AIN4	General purpose I/O TAMPC active shield 3 output RADIO DFEGPIO Analog input	Clock pin TAMPC RADIO
36	P0.03/CLK	28	P0.03/GRTC_PWMOUT	General purpose I/O GRTC PWM output	Clock pin GRTC
37	P2.10	21	P2.10/TRACEDATA[3]/SPIM.CS	General purpose I/O Trace SPIM CS UARTE RTS	Trace SPIM00/SPIM21 UARTE00/UARTE21
38	P2.06/CLK	17	P2.06/TRACECLK/SPI.SCK	General purpose I/O SPIM SCK SPIS SCK Trace clock	Clock pin SPIM00/SPIM21 SPIS00/SPIS21 Trace
39	GND				
Pin Definition Notes:					

Pin #	Pin Name (red coloured pins for clock for interfaces, trace)	nRF54L15	nRF54L15/ nRF54L10 QFN48	Description	Example usage
	Note 1	GPIO = General Input or Output (GPIO level voltage tracks VDD pin). AIN =Analog input.			
	GPIO	If GPIO is selected as an input, ensure the input is not floating (which can cause current consumption to drive with time in low power modes (such as System ON Idle), by selecting the internal pull up or pull down. Must connect all GND pads to host board PCB GND plane.			
	Note2	Some peripherals (SPI, TWI, PDM, I2S, TRACE, GRTC) have clock signals. Dedicated clock pins have been optimized to ensure correct timing relationship between clock and data signal for these peripherals. Pins that can be used as clock signals are shown with pin name in red colour.			
	Clock for serial interfaces or trace	The peripheral data signal must be configured to use pins close to the clock pin. This ensures that the internal paths from the peripheral to the pin have the same delay, so that the data and clock signals reach the pins at the same time. For high-speed signals, the printed circuit board (PCB) layout must use short PCB traces of identical length. This makes sure any delays are kept to a minimum and it assures close to identical delay and clock path.			
	Note 3	UART20/21:	Can use any pin son GPIO port P1. Can be connected across power domains to dedicated pin on P2.		
	Dedicated pins	SPIM00:	Has dedicated pins on GPIO port P2. For 32MHz operation, the pins must be configured using extra high drive E0/E1 configuration.		
		SPIM20/21:	Can use any pin son GPIO port P1. Can be connected across power domains to dedicated pin on P2.		
		SPIS20/21:	Can use any pin son GPIO port P1. Can be connected across power domains to dedicated pin on P2.		
		TRACE:	Has dedicated pins on GPIO port P2. For 32MHz operation, the pins must be configured using extra high drive E0/E1 configuration.		
		GRTC:	Has dedicated pins for clock and PWM output.		
		TAMPC:	Has dedicated pins for active shield inputs and outputs.		
		FLPR:	Uses dedicated pins on GPIO port P2 for emulated peripherals such as QSPI.		
		RADIO:	Uses dedicated pins on GPIO port P1 for antenna switch control (DFEGPIO for direction finding).		
		NFC:	Uses dedicated pins listed in pin definitions table1.		
	Note 4	Customer MUST bring out SWDIO, SWCLK, nRESET, VDD, GND for programming purposes.			
	SWDIO / SWCLK / nRESET / VDD / GND				

3.3 Electrical Specifications

3.3.1 Absolute Maximum Ratings

Absolute maximum ratings are the extreme limits for supply voltage and voltages on digital and analogue pins of the module are listed below; exceeding these values causes permanent damage.

Table 2: Absolute maximum ratings

Parameter	Min	Max	Unit
Supply Voltages			
VDD_nRF	-0.3	3.6	V
I/O pin voltage			
Voltage at GPIO pin (at VDD≤3.5V)	-0.3	VDD_nRF + 0.3	V
Voltage at GPIO pin (at VDD>3.5V)		3.6	V
NFC antenna pin current (NFC1/2)	-	130	mA
Environmental			
Storage temperature	-40	+105	°C
MSL (Moisture Sensitivity Level)	-	4	-
ESD (as per EN301-489)			
Conductive		4	kV
Air Coupling		8	kV
Flash Memory (Endurance) (Note 2)	10,000		Write/erase cycles
Flash Memory (Retention)	10 years at 85°C		years at TBD °C
	2 years at 105°C		

Absolute maximum Ratings Notes:

Note 1 The absolute maximum rating for VDD pin (max) is 3.6 V for the BL54L15.

Note 2 Wear levelling can be implemented by customer.

3.3.2 Recommended Operating Parameters

Table 3: Power supply operating parameters

Parameter	Min	Typ	Max	Unit
VDD_nRF (independent of DCDC) supply range	1.7		3.5	V
VDD_nRF _{ext} (VDD_nRF supply voltage under extended operating temperature)	1.7		3.3	V
VDD_nRF Maximum ripple or noise (See Note 1)	-	-	10	mV
Operating Temperature Range	-40	+25	+85	°C
Extended operating temperature	85		105	°C

Recommended Operating Parameters Notes:

Note 1 This is the maximum VDD_nRF ripple or noise (at any frequency) that does not disturb the radio.

Note 2 The on-board power-on reset circuitry may not function properly for rise times longer than the specified maximum.

Note 3 Some electrical parameters are valid only for the operating temperature range conditions. When this is the case, an additional parameter for the extended operating temperature condition is provided.

3.4 Clocks

3.4.1 HFXO - 32MHz crystal oscillator and nRF54L15/nRF54L10 internal load capacitor mandatory setting

The BL54L15/BL54L10 module contains the 32 MHz crystal, but the load capacitors to create 32MHz crystal oscillator circuit are inside the nRF54L15/nRF54L10 chipset. Customer can set the internal nRF54L15/nRF54L10 capacitors from 4 pF to 17 pF in 0.25pF if needed or use default value without changing.

The 32 MHz crystal inside the BL54L15/BL54L10 module is a high accuracy crystal (± 15 ppm at room temperature) that helps with radio operation and reducing power consumption in the active modes.

3.4.2 LFCLK – Low Frequency clock source

There are four possibilities (see figure 5) for the low frequency clock (LFCLK) and options are:

LFRC (32.768kHz RC oscillator): The Internal 32.768 kHz RC oscillator (LFRC) is fully embedded in nRF54L15/nRF54L10 (and does not require additional external components) with an accuracy ± 250 ppm (after calibration of LFRC at least every eight seconds using the HFXO as a reference oscillator).

LF XO (32.768kHz crystal oscillator): For higher LFCLK accuracy (greater than ± 250 ppm accuracy is required), the low frequency crystal oscillator (LF XO) must be used. To use LF XO, a 32.768kHz crystal must be connected between the XL1 and XL2 pins and the load capacitance between each crystal terminal and ground. Optionally internal (to nRF54L15/nRF54L10) capacitor of maximum 18 pF in 0.5 pF steps are provided on pins XL1 and XL2.

Low frequency (32.768 kHz) external source: The 32.768 kHz oscillator (LF XO) is designed to work with external sources

LFSYNTH (32.768kHz Synthesised clock) from HFCLK (LFSYNTH): The LFCLK can be synthesised from the HFCLK source. LFSYNTH depends on the HFCLK to run. The accuracy of the LFCLK clock with LFSYNTH as a source assumes the accuracy of the HFCLK. If high accuracy is required, the HFCLK must be generated from the HFXO. Using the LFSYNTH clock removes the requirement for an external 32.768kHz crystal but the increases the average power consumption as the HFCLK will be turned on in the system.

The diagram illustrates the clock system architecture, divided into two main functional areas: **Oscillators** and **Clock**.

Oscillators:

- HFCLK section:** Includes an **Internal oscillator** and an **HF XO crystal oscillator** (labeled 32 MHz). Both feed into a **PLL** (Phase-Locked Loop).
- LFCLK section:** Includes an **LF XO 32.768 kHz crystal oscillator** (labeled 32.768 kHz).

Clock:

- The **PLL** output feeds the **HFCLK oscillator control** block.
- The **LF XO** output feeds the **LFCLK oscillator control** block.
- The **HFCLK oscillator control** block also feeds into **CAL** (Calibration) and **SYNT** (Synthesizer) blocks.
- CAL** and **SYNT** both feed into the **LFCLK RC oscillator** block.
- The **LFCLK RC oscillator** block feeds into the **LFCLK oscillator control** block.
- The **LFCLK oscillator control** block feeds into the **LFCLK clock control** block.
- The **HFCLK oscillator control** block feeds into the **HFCLK clock control** block.

Outputs:

- The **HFCLK clock control** block outputs **HFCLOCKS** (see following table for details).
- The **LFCLK clock control** block outputs **PCLK32KI**, **GRTC.LFLPRC**, and **GRTC.LFXO**.

3.5 BL54L15/ BL54L10 Power Supply

[illegible]

<https://www.ezurio.com/>

4 Programmability

4.1 BL54L15/ BL54L10 Default Firmware

The BL54L15/BL54L10 module is shipped from Ezurio manufacturing facilities with no firmware programmed.

4.2 BL54L15/ BL54L10 Firmware Options

Firmware for use with the BL54L15/BL54L10 can be divided into the following types.

- Bootloader** – This is the application that resides on the Application Core used to perform firmware updates of the Application and FLPR cores.

The MCU Boot or Trusted Firmware M Bootloaders are recommended to be used as the basis for the BL54L15 Bootloader functionality.
- Application** – This is the main application running on the Application core. It interfaces with the integrated radio stack(s) and provides supplementary functionality in addition to the time critical activities performed for radio activity.
- Software Defined Peripheral** – This is the application running on the RISC-V FLPR core.

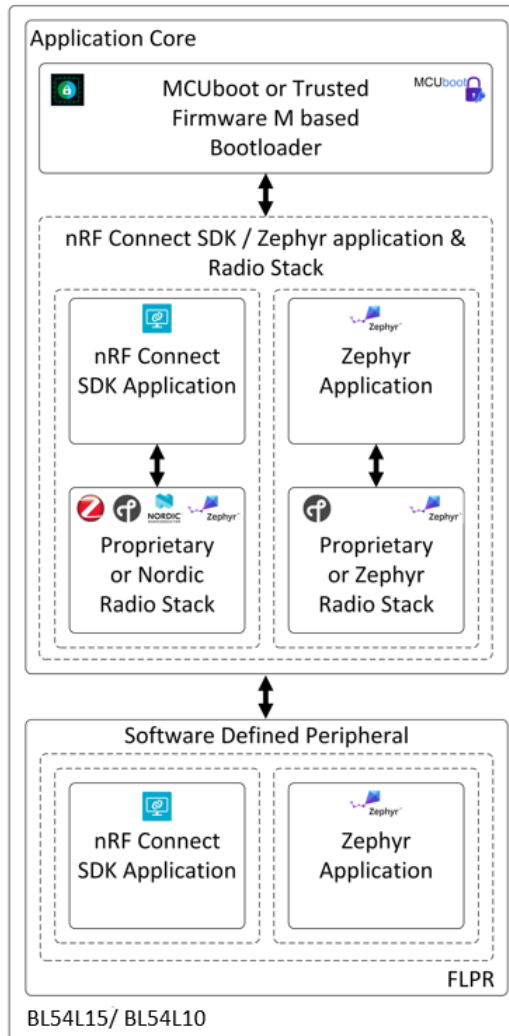


Figure 5 : Functional SW block diagram for BL54L15/BL54L10 series module

5 Peripherals

Feature		Module	
		BL54L15	BL54L10
		nRF54L15-QFAA	nRF54L10-QFAA
Memory	Non-volatile memory (RRAM)	1524 KB	1022 KB
	Random access memory (RAM)	256 KB	192 KB
Radio	Bluetooth Low Energy	Yes	
	Bluetooth Low Energy Coded PHY (Long range)	Yes	
	Bluetooth Constant Tone Extension (Direction-finding)	Yes	
	IEEE 802.15.4	Yes	
GPIO pins	GPIO pins	31	
	Wakeup-pins	20	
	Analog input pins	8	
	GPIO voltage	VDD (1.7V-3.5V)	
Peripherals	Timers (TIMER)	7	
	Real-time counter (RTC)	2	
	Global real-time counter (GRTC)	Yes	
	Serial interfaces (UART, SPI, TWI)	5	
	Temperature sensor	Yes	
	Comparator (COMP)	Yes	
	Analog-to-digital converter (ADC)	Yes	
	Quadrature decoder (QDEC)	2	
	Inter-IC sound interface (I2S)	2	
	Near-field communication (NFC)	Yes	
	Pulse density modulation interface (PDM)	2	
	Pulse-width modulator (PWM)	3	
	Watchdog timer (WDT)	2	
	Active tamper shield pin pairs (in/out)	4	
	Glitch detectors	Yes	
	Key management unit	Yes	
Security	Encryption accelerator	Yes	
	ITM parallel trace	Yes	
Debug		Yes	

6 SW requirements related to hardware

6.1 32MHz crystal internal load capacitor setting

BL54L15/ BL54L10 module contains the 32 MHz crystal but the load capacitors to create 32 MHz crystal oscillator circuit are inside the nRF54L15/ nRF54L10 chipset. Customer can set the internal nRF54L15/nRF54L10 capacitors from 4 pF to 17 pF in 0.25pF if needed, or use default value without changing.

7 Hardware Integration Suggestions

7.1 Circuit

The BL54L15/ BL54L10 is easy to integrate, requiring one mandatory external 10uF capacitor on customers board and apart from that those components which customer require for development and in your end application.

The following are suggestions for your design for the best performance and functionality.

Checklist (for Schematic):

- **BL54L15/ BL54L10 power supply:**

Normal voltage mode power supply mode is entered when the external supply voltage (1.7V-3.5V) is connected to both VDD_nRF pin (pin26).

External power source should be within the operating range, rise time and noise/ripple specification of the BL54L15/ BL54L10. Add decoupling capacitors for filtering the external source. Power-on reset circuitry within BL54L15/ BL54L10 series module incorporates brown-out detector, thus simplifying your power supply design. Upon application of power, the internal power-on reset ensures that the module starts correctly.

- **AIN (ADC) and GPIO pin IO voltage levels**

BL54L15/BL54L10 GPIO voltage levels are at VDD_nRF. Ensure input voltage levels into GPIO pins are at VDD_nRF also. Ensure ADC pin maximum input voltage for damage is not violated.

- **AIN (ADC) impedance and external voltage divider setup**

If you need to measure with ADC a voltage higher than 3.5V, you can connect a high impedance voltage divider to lower the voltage to the ADC input pin.

- **SWD**

This is REQUIRED for loading firmware. MUST wire out the SWD two wire interface on host design. Five lines should be wired out, namely SWDIO, SWDCLK, nRESET, GND and VDD.

- **UART and flow control (CTS, RTS)**

Required if customer requires UART.

- **I2C (I2C)**

It is essential to remember that pull-up resistors on both SCL and SDA lines are required, the value as per I2C standard. nRF54L15/ nRF54L10 can provide 13K Ohms typical pull up values internally. For other values, fit external pull-up resistor on both SCL and SDA as per I2C specification to set speed. The I2C specification allows a line capacitance of 400pF.

- **QSPI, High Speed SPI, High speed TWI (I2C, 1Mbps) and Trace**

High-Speed SPI, TWI and Trace come on dedicated GPIO pins only. Other lower speed SPI and TWI can come out on any GPIO pins.

For all high-speed signal, the printed circuit board (PCB) layout must ensure that connections are made using short PCB traces.

- **GPIO pins**

If GPIO is selected as an input, ensure the input is not floating (which can cause current consumption to drive with time in low power modes (such as System ON Idle), by selecting the internal pull up or pull down.

- **NFC antenna connector**

- To make use of the Ezurio flexi-PCB NFC antenna (part # 0600-00061), fit connector:

- Description – FFC/FPC Connector, Right Angle, SMD/90d, Dual Contact, 1.2 mm Mated Height
- Manufacturer – Molex
- Manufacturers Part number – 512810594

Add tuning capacitors of 300 pF on NFC1 pin to GND and 300 pF on NFC2 pins to GND if the PCB track length is similar as development board.

- **nRESET pin (active low)**

Hardware reset. Wire out to push button or drive by host.

By default module is out of reset when power applied to VDD_nRF pins (13K pull-up inside BL54L15/ BL54L10 (nRF54L15-QFAA/nRF54L10-QFAA)).

- **Optional External 32.768kHz crystal**

If the optional external 32.768kHz crystal is needed, then use a crystal that meets specification and add load capacitors (either inside nRF54L15-QFAA/nRF54L10-QFAA or discrete capacitors outside BL54L15/BL54L10 (nRF54L15-QFAA/nRF54L10-QFAA) whose values should be tuned to meet all specification for frequency and oscillation margin.

7.2 PCB Layout on Host PCB - General

Checklist (for PCB):

- MUST locate BL54L15/ BL54L10 module close to the edge of PCB (mandatory for the 453-00001/453-00225 for on-board PCB trace antenna to radiate properly).
- Use solid GND plane on inner layer (for best EMC and RF performance).
- All module GND pins MUST be connected to host PCB GND.
- Place GND vias close to module GND pads as possible.
- Unused PCB area on surface layer can be flooded with copper but place GND vias regularly to connect the copper flood to the inner GND plane. If GND flood copper is on the bottom of the module, then connect it with GND vias to the inner GND plane.
- Route traces to avoid noise being picked up on VDD_nRF supply and AIN (analogue), GPIO (digital) traces and high-speed traces.
- Ensure no exposed copper is on the underside of the module (refer to land pattern of BL54L15/BL54L10 development board).

7.3 PCB Layout on Host PCB for the 453-00001 and 453-00225

7.3.1 Antenna Keep-out on Host PCB

The 453-00001/453-00225 has an integrated PCB trace antenna and its performance is sensitive to host PCB. It is critical to locate the 453-00001/453-00225 on the edge of the host PCB (or corner) to allow the antenna to radiate properly. Refer to guidelines in section **PCB land pattern and antenna keep-out area for the 453-00001/453-00225**. Some of those guidelines repeated below.

- Ensure there is no copper in the antenna keep-out area on any layers of the host PCB. Keep all mounting hardware and metal clear of the area to allow proper antenna radiation.
- For best antenna performance, place the 453-00001/453-00225 module on the edge of the host PCB, preferably in the edge center.
- The BL54L15 development board (453-00001-K1) has the 453-00001 module on the edge of the board (not in the corner). The antenna keep-out area is defined by the BL54L15 development board which was used for module development and antenna performance evaluation is shown in Figure 6, where the antenna keep-out area is ~5mm wide, ~28.6mm long; with PCB dielectric (no copper) height ~1.57mm sitting under the 453-00001 PCB trace antenna module. BL54L10 module (453-00225) please follow the same design of BL54L15.
- The 453-00001 PCB trace antenna is tuned when the 453-00001 is sitting on development board (host PCB) with size of 113 mm x 63.5 mm x 1.6mm.
- A different host PCB thickness dielectric will have small effect on antenna.
- The antenna-keep-out defined in the 8.2 Host PCB Land Pattern and Antenna Keep-out for the 453-00001 and 453-00225 section.
- Host PCB land pattern and antenna keep-out for the BL54L15/BL54L10 applies when the 453-00001/453-00225 is placed in the edge of the host PCB preferably in the edge center. 錯誤! 找不到參照來源 • shows an example.

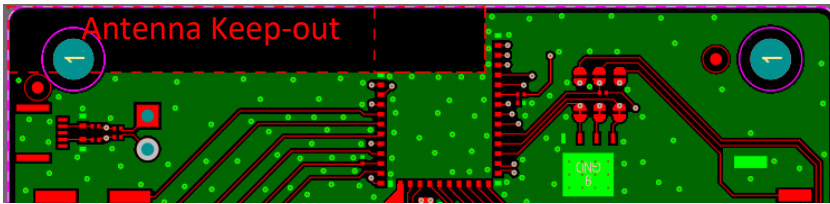


Figure 6 : PCB trace Antenna keep-out area (shown in red), corner of the BL54L15 development board for the 453-00001 module.

Antenna Keep-out Notes:

- Note 1** The BL54L15/BL54L10 module is placed on the edge, preferably edge centre of the host PCB.
- Note 2** Copper cut-away on all layers in the *Antenna Keep-out* area under the 453-00001/453-00225 on host PCB.

7.3.2 Antenna Keep-out and Proximity to Metal or Plastic

Checklist (for metal /plastic enclosure):

- Minimum safe distance for metals without seriously compromising the antenna (tuning) is 40 mm top/bottom and 30 mm left or right.
- Metal close to the 453-00001/453-00225 PCB trace monopole antenna (bottom, top, left, right, any direction) will have degradation on the antenna performance. The amount of that degradation is entirely system dependent, meaning you will need to perform some testing with your host application.
- Any metal closer than 20 mm will begin to significantly degrade performance (S11, gain, radiation efficiency).
- It is best that you test the range with a mock-up (or actual prototype) of the product to assess effects of enclosure height (and materials, whether metal or plastic) and host PCB ground (GND plane size).

7.4 External Antenna Integration with BL54L15/BL54L10 MHF4 variant (453-00044/453-00226)

Please refer to the regulatory sections for FCC, ISED, CE, MIC, UKCA and RCM details of use of BL54L15 with external antennas in each regulatory region.

The BL54L15/BL54L10 family has been designed to operate with the below external antennas (with a maximum gain of 2.32 dBi). The required antenna impedance is 50 ohms. See [Table 4](#). External antennas improve radiation efficiency.

Table 4: External antennas for the BL54L15/BL54L10 RF trace pin variant module (453-00044/453-00226)

Manufacturer	Model	Ezurio Part Number	Type	Connector	Peak Gain	
					2400-2500 MHz	2400-2480 MHz
Ezurio (Laird Connectivity)	NanoBlue	EBL2400A1-10MH4L	PCB Dipole	IPEX MHF4	2 dBi	-
Ezurio (Laird Connectivity)	FlexPIFA	001-0022	PIFA	IPEX MHF4	-	2 dBi
Mag.Layers	EDA-8709-2G4C1-B27-CY	0600-00057	Dipole	IPEX MHF4	2.32 dBi	-
Ezurio (Laird Connectivity)	mFlexPIFA	EFA2400A3S-10MH4L	PIFA	IPEX MHF4	-	2 dBi
Ezurio (Laird Connectivity)	iFlexPIFA Mini	EFG2401A3S-10MH4L	PIFA	IPEX MHF4	-	2 dBi
Ezurio (Laird Connectivity)	Ezurio NFC	0600-00061	NFC	N/A	-	-

8 Mechanical Details

8.1 BL54L15/BL54L10 Mechanical Details

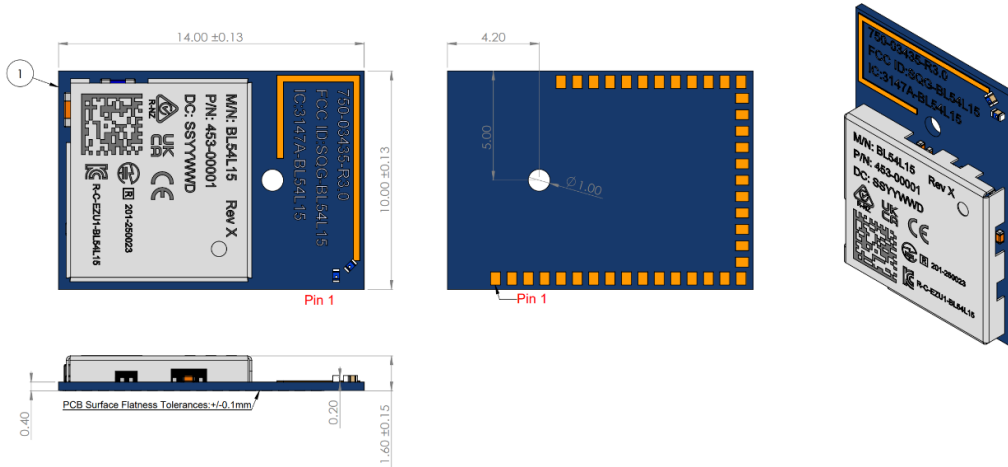


Figure 7 : Mechanical Details – Internal Antenna variant module (453-00001)

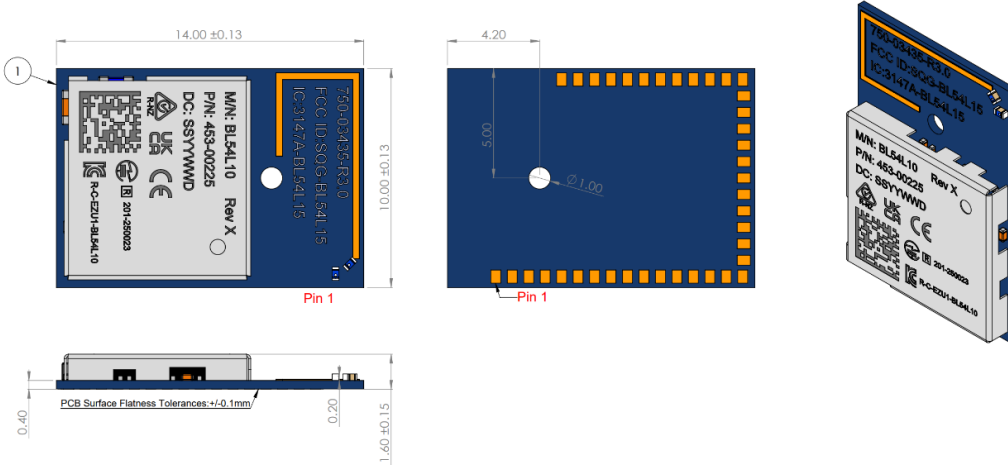


Figure 8 : Mechanical Details – Internal Antenna variant module (453-00225)

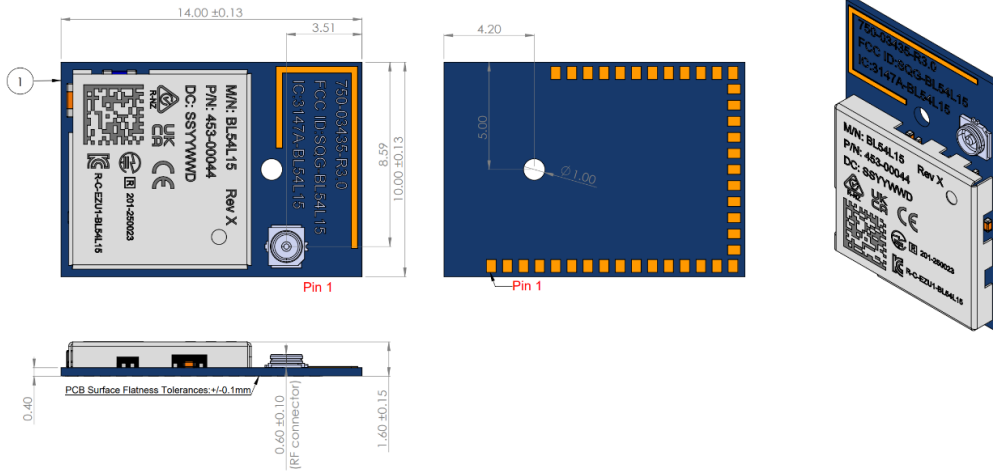


Figure 9 : Mechanical Details – MHF4 RF connector variant module (453-00044)

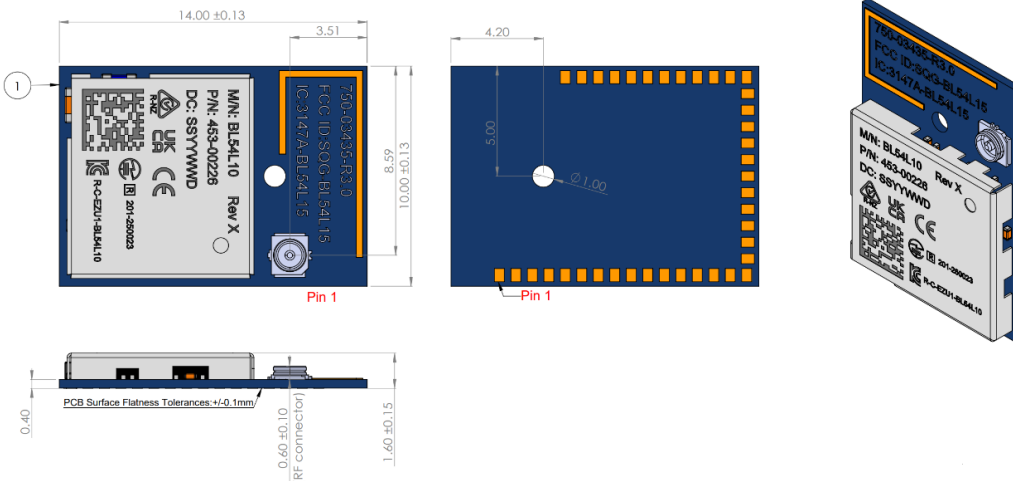


Figure 10 : Mechanical Details – MHF4 RF connector variant module (453-00226)

3D models for BL54L15 Module, MHF4 (453-00044) and BL54L15 Module, Trace Antenna (453-00001) on the BL54L15 product page – <https://www.ezurio.com/product/bl54l15-series-bluetooth-le-80215-4-nfc>

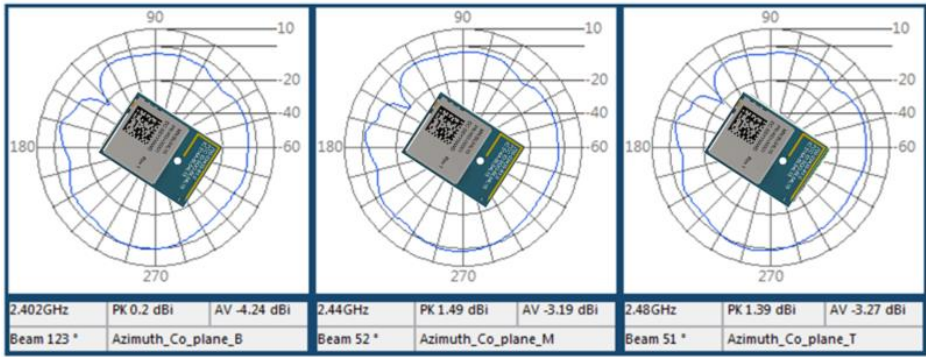
9 On -Board PCB Trace Antenna Characteristics

9.1 Summary of Antenna Performance

453-00001/453-00225 PCB trace antenna	+0.2dBi	-4.24dBi	+1.49dBi	-3.19dBi	+1.39dBi	-3.27dBi
---------------------------------------	---------	----------	----------	----------	----------	----------

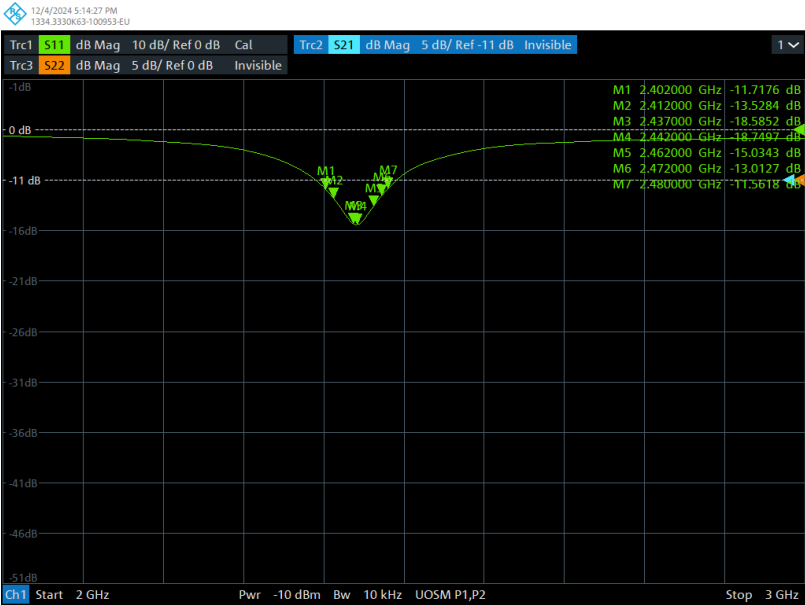
已註解 [JK3]: @Li Yuan Chang is this information the same for the L10 versions, as written below is only specific to L15.

9.2 2.4GHz Radiated Performance



已註解 [LC4R3]: Antenna is same for L15 and L10, so add 453-00225 here.

9.3 Antenna S11 measuring data



10 Application Note for Surface Mount Modules

10.1 Introduction

Ezurio's surface mount modules are designed to conform to all major manufacturing guidelines. This application note is intended to provide additional guidance beyond the information that is presented in the user manual. This application note is considered a living document and will be updated as new information is presented.

The modules are designed to meet the needs of several commercial and industrial applications. They are easy to manufacture and conform to current automated manufacturing processes.

Part numbers – 453-00001R/453-00225R and 453-00044R/453-00226R are shipped as Tape / Reel, with a reel containing 1,000 pcs.

10.2 Module Packaging Configuration

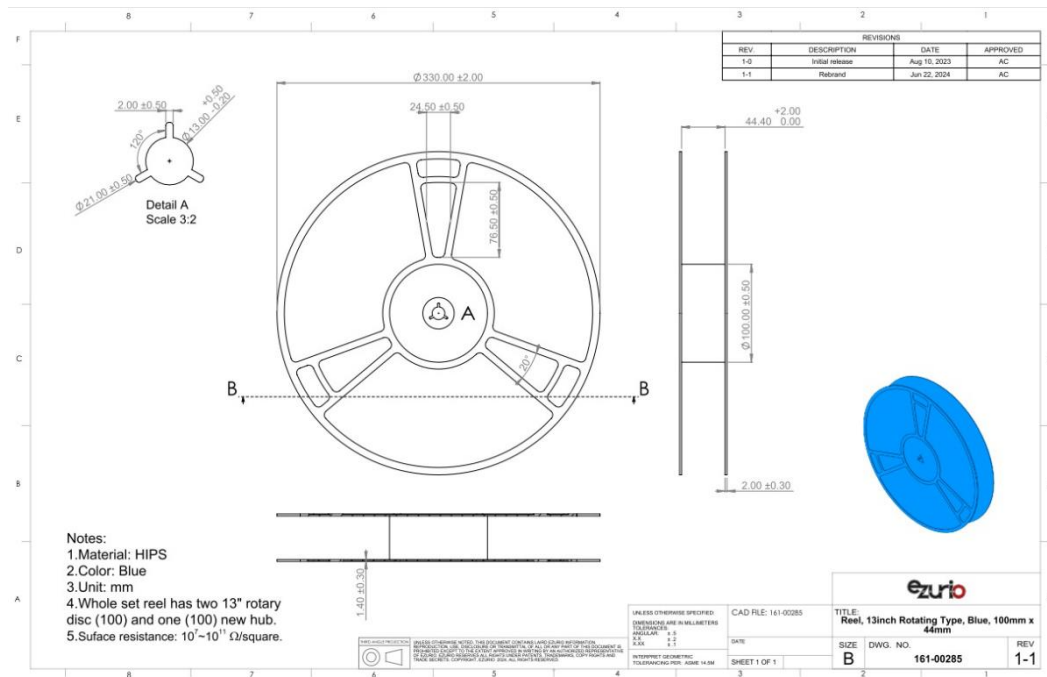


Figure 12: Reel specifications – 1,000 pieces per reel

已註解 [LYC5]: This chapter needs to be confirmed

已註解 [JK6R5]: @Connie Lin please can you review this section and confirm is all accurate and correct.

已註解 [CL7R5]: This is all correct.



Figure 14: BL54L15/BL54L10 Packaging Process



All modules are shipped in tape and reel package and sealed in ESD Bags.

已註解 [CL9R8]: MSL4; I corrected the packaging information.

10.4 Labeling

The following labels are placed on the anti-static bag. The BL54L15/BL54L10 modules are classified as MSL4 devices.

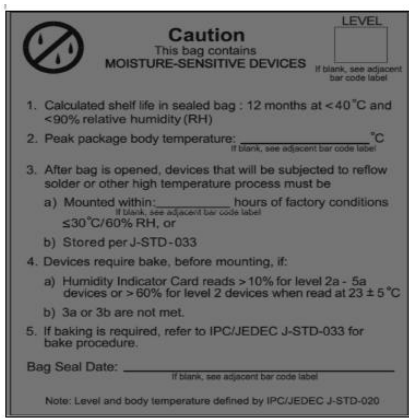


Figure 15: Moisture Sensitivity Level Label



Figure 16: Product Identifier Label

已註解 [JK10]: What MSL level @ Connie?

已註解 [CL11R10]: @Jonathan Kaye MSL4. I added it to this section

The following labels are placed on the pizza box.

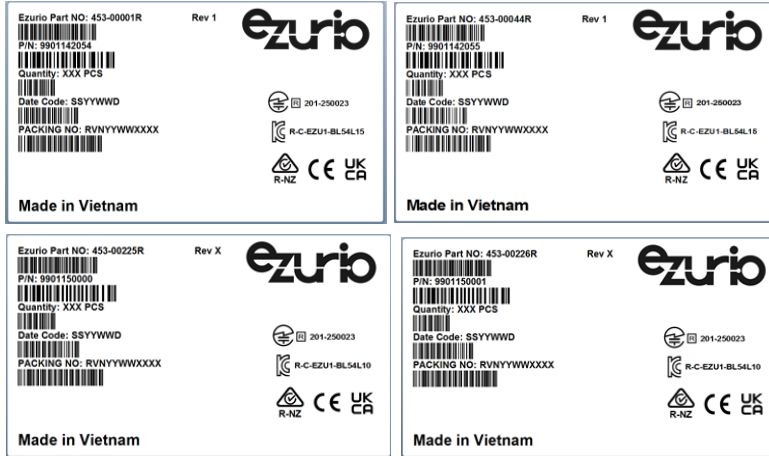


Figure 17: Product Identifier Label

The following labels are placed on the master shipping carton.



Figure 18: Standard Shipping Carton Label

10.5 Required Storage Conditions

10.5.1 Prior to Opening the Dry Packing

The following are required storage conditions *prior to opening the dry packing*:

- Normal temperature: 5~40°C
- Normal humidity: 80% (Relative humidity) or less
- Storage period: One year or less

Note: Humidity means relative humidity.

10.5.2 After Opening the Dry Packing

The following are required storage conditions *after opening the dry packing* (to prevent moisture absorption):

- Storage conditions for one-time soldering:
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: 72 hours or less after opening
- Storage conditions for two-time soldering
 - Storage conditions following opening and prior to performing the 1st reflow:
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: A hours or less after opening
 - Storage conditions following completion of the 1st reflow and prior to performing the 2nd reflow
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: B hours or less after completion of the 1st reflow

Note: Should keep A+B within 72 hours.

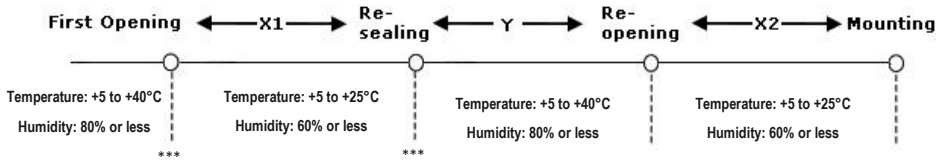
10.5.3 Temporary Storage Requirements after Opening

The following are temporary storage requirements after opening:

- Only re-store the devices *once* prior to soldering.
- Use a dry box or place desiccant (with a blue humidity indicator) with the devices and perform dry packing again using vacuumed heat-sealing.

The following indicate the required storage period, temperature, and humidity for this temporary storage:

- Storage temperature and humidity:



- Storage period:
 - X1+X2 – Refer to **After Opening the Dry Packing** storage requirements. Keep is X1+X2 within 72 hours.
 - Y – Keep within two weeks or less.

10.6 Baking Conditions

Baking conditions and processes for the module follow the J-STD-033 standard which includes the following:

- The calculated shelf life in a sealed bag is 12 months at <40°C and <80% relative humidity.
- Once the packaging is opened, the module must be mounted (per MSL4/Moisture Sensitivity Level 4) within 72 hours at <30°C and <60% relative humidity.
- If the module is not mounted within 72 hours or if, when the dry pack is opened, the humidity indicator card displays >10% humidity, then the product must be baked for 48 hours at 125 °C (±5 °C).

10.7 Surface Mount Conditions

The following soldering conditions are recommended to ensure device quality.

10.7.1 Soldering

Note: When soldering, the stencil thickness should be ≥ 0.1 mm.

Convection reflow or IR/Convection reflow (one-time soldering or two-time soldering in air or nitrogen environment)

- Measuring point – IC package surface
- Temperature profile:

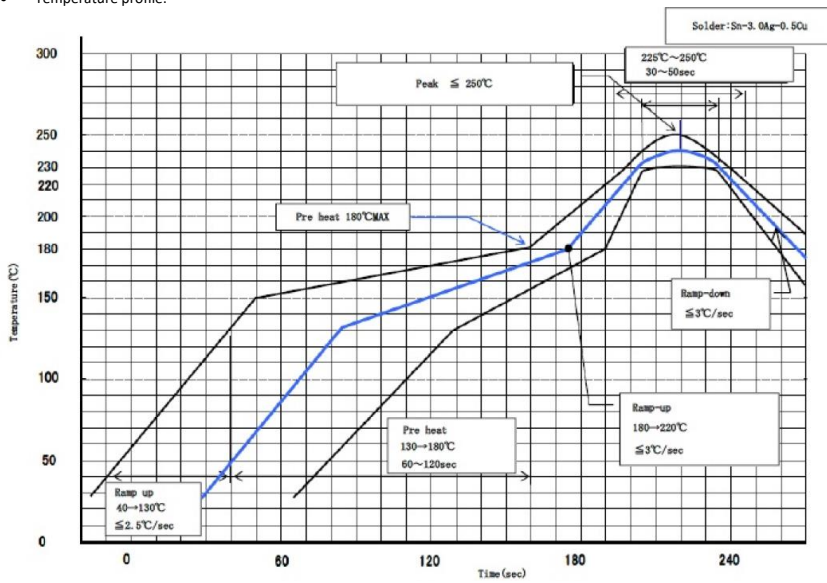


Figure 19: Temperature profile

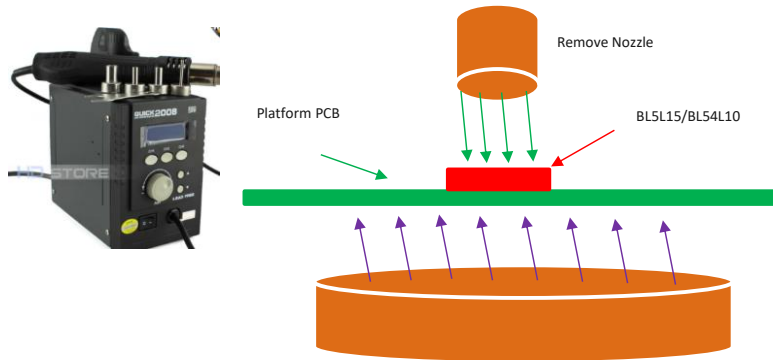
- Ramp-up: $40 \sim 130^{\circ}\text{C}$. Less than 2.5°C/sec
- Pre heat: $130 \sim 180^{\circ}\text{C}$ $60 \sim 120$ sec, 180°C MAX
- Ramp-up: $180 \sim 220^{\circ}\text{C}$. Less than 3°C/sec
- Peak Temperature: MAX 250°C
 - $225^{\circ}\text{C} \sim 250^{\circ}\text{C}$, $30 \sim 50$ sec
- Ramp-down: Less than 3°C/sec

10.7.2 Cautions When Removing the BL54L15/BL54L10 from the Platform for RMA

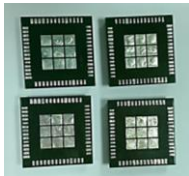
- Bake the platform before removing the BL54L15/BL54L10 from the platform. Reference baking conditions.
- Remove the BL54L15/BL54L10 by using a hot air gun. This process should be carried out by a skilled technician.

Suggestion conditions:

- One-side component platform:
 - Set the hot plate at 280° C.
 - Put the platform on the hot plate for 8~10 seconds.
 - Remove the SIP from platform.
- Two-side components platform:
 - Use two hot air guns
 - On the bottom side, use a pre-heated nozzle (temperature setting of 200~250° C) at a suitable distance from the platform PCB.
 - On the top side, apply a remove nozzle (temperature setting of 330° C). Heat the SIP until it can be removed from platform PCB.



- Remove the residue solder under the bottom side of module. (Note: Alternate module pictured as an example)



(Not accepted for RMA)



(Accepted for RMA analysis)

Example module with residue solder on the bottom Example Module, no residue solder

- Remove and clean the residue flux as needed.

10.7.3 Precautions for Use

- Opening/handling/removing must be done on an anti-ESD treated workbench. All workers must also have undergone anti-ESD treatment.
- The devices should be mounted within one year of the date of delivery.
- The BL54L15/BL54L10 modules are MSL 4 rated.

已註解 [JK12]: @L Yuan Chang can you check whether this is relevant here - what SIP? Or we mean take the L15 / L10 module off a host PCB?

已註解 [LC13R12]: Yes, it means take L15/L10 off PCB, I update here.

11 Reliability Test

11.1 Climatic And Dynamic Reliability Test

Table 5: Climatic and Dynamic Reliability Test Results for BL54L15/BL54L10 Modules

Test Item	Specification	Standard	Test Result
Thermal Shock	Temperature: -40 ~ 85°C Ramp time: Less than 10 seconds. Dwell Time: 10 minutes Number of Cycles: 350 times	*JESD22-A106 *IEC 60068-2-14 for dwell time and number of cycles	PASS
Vibration Non-Operating Unpackaged device	Vibration Wave Form: Sine Waveform Vibration frequency / Displacement: 20-80 Hz/1.5mm Vibration frequency / Acceleration: 80-2000 Hz/20g Cycle Time: 4 min/cycle Number of Cycles: 4 cycle/axis Vibration Axes: X, Y and Z (Rotate each axis on vertical vibration table)	JEDEC 22-B103B (2016)	PASS
Mechanical Shock Non-Operating Unpackaged device	Pulse shape: Half-sine waveform Impact acceleration: 1500 g Pulse duration: 0.5 ms Number of shocks: 30 shocks (5 shocks for each face) Orientation: Bottom, top, left, right, front, and rear faces	JEDEC 22-B110B.01 (2019)	PASS

11.2 Reliability MTBF Prediction

Table 6: MTBF Predictions for BL54L15/BL54L10 Modules

Ezurio Part Number	Environment	Standard	Test Result 45 °C (Hours)
453-00001R	Ground, Fixed, Uncontrolled	Telcordia Issue 4	1,559,211
453-00001C			
453-00225R			
453-00225C			
453-00044R	Ground, Fixed, Uncontrolled	Telcordia Issue 4	1,559,211
453-00044C			
453-00226R			
453-00226C			
453-00001R	Mobile, Fixed, Uncontrolled	Telcordia Issue 4	605,957
453-00001C			
453-00225R			
453-00225C			
453-00044R	Mobile, Fixed, Uncontrolled	Telcordia Issue 4	605,957
453-00044C			
453-00226R			
453-00226C			
Ezurio Part Number	Environment	Standard	Test Result 105 °C (Hours)
453-00001R	Ground, Fixed, Uncontrolled	Telcordia Issue 4	980,517
453-00001C			
453-00225R			
453-00225C			
453-00044R	Ground, Fixed, Uncontrolled	Telcordia Issue 4	980,517
453-00044C			
453-00226R			
453-00226C			
453-00001R	Mobile, Fixed, Uncontrolled	Telcordia Issue 4	283,138
453-00001C			
453-00225R			
453-00225C			
453-00044R	Mobile, Fixed, Uncontrolled	Telcordia Issue 4	283,138
453-00044C			
453-00226R			
453-00226C			

12 Regulatory

Full regulatory information on the BL54L15/BL54L10, including the Regulatory Information Guide, grants, and test reports are available on the [BL54L15 product page](#) and [BL54L10 product page](#).

The BL54L15/BL54L10 holds current certifications in the following countries:

Table 7: BL54L15 Certifications

Country/Region	Regulatory ID
USA (FCC)	SQG-BL54L15
EU (ETSI)	N/A (No ID Number Required)
UKCA	N/A (No ID Number Required)
Canada (ISED)	3147A-BL54L15
Japan (MIC)	201-250023
Australia (RCM)	N/A
New Zealand (RCM)	N/A
Korea	R-C-EZU1-BL54L15 (for BL54L15) R-C-EZU1-BL54L10 (for BL54L10)

已註解 [JK14]: @Yuan Chang @Dave Drogowski Need to keep an eye on this. The datasheet covers both L15 and L10 - are these IDs correct for L10 please?

已註解 [LC15R14]: This table is correct, only Korea needs to be separated, others can be the same.

12.1 Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the

following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

IMPORTANT NOTE:

FCC Radiation Exposure Statement:

The product comply with the US portable RF exposure limit set forth for an uncontrolled environment and are safe for intended operation as described in this manual. The further RF exposure reduction can be achieved if the product can be kept as far as possible from the user body or set the device to lower output power if such function is available.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

Integration instructions for host product manufacturers**Applicable FCC rules to module**

FCC Part 15.247

Summarize the specific operational use conditions

This device is intended only for OEM integrators under the following conditions:

- 1) The transmitter module may not be co-located with any other transmitter or antenna

As long as 1 condition above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

IMPORTANT NOTE: In the event that these conditions can not be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID can not be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization. The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

Limited module procedures

Not applicable

Trace antenna designs

Not applicable

RF exposure considerations

Co-located issue shall be met as mentioned in "Summarize the specific operational use conditions".

Product manufacturer shall provide below text in end-product manual

"FCC Radiation Exposure Statement:

The product comply with the US portable RF exposure limit set forth for an uncontrolled environment and are safe for intended operation as described in this manual. The further RF exposure reduction can be achieved if the product can be kept as far as possible from the user body or set the device to lower output power if such function is available."

Label and Compliance Information

Product manufacturers need to provide a physical or e-label stating

"Contains FCC ID: **SQG-BL54L15**" with finished product

Information on Test Modes and Additional Testing Requirements

Test tool: **Putty**, **Version:0.60** shall be used to set the module to transmit continuously.

Additional Testing, Part 15 Subpart B Disclaimer

The module is only FCC authorized for the specific rule parts listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed

12.2 Industry Canada statement

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

- (1) This device may not cause interference
(2) This device must accept any interference, including interference that may cause undesired operation of the device

L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- (1) L'appareil ne doit pas produire de brouillage;
(2) L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Radiation Exposure Statement:

The product comply with the Canada portable RF exposure limit set forth for an uncontrolled environment and are safe for intended operation as described in this manual. The further RF exposure reduction can be achieved if the product can be kept as far as possible from the user body or set the device to lower output power if such function is available.

Déclaration d'exposition aux radiations:

Le produit est conforme aux limites d'exposition pour les appareils portables RF pour les Etats-Unis et le Canada établies pour un environnement non contrôlé. Le produit est sûr pour un fonctionnement tel que décrit dans ce manuel. La réduction aux expositions RF peut être augmentée si l'appareil peut être conservé aussi loin que possible du corps de l'utilisateur ou que le dispositif est réglé sur la puissance de sortie la plus faible si une telle fonction est disponible.

This device is intended only for OEM integrators under the following conditions:

- 1) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 1 condition above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Cet appareil est conçu uniquement pour les intégrateurs OEM dans les conditions suivantes:

- 1) Le module émetteur peut ne pas être coïmplanté avec un autre émetteur ou antenne.

Tant que les 1 condition ci-dessus sont remplies, des essais supplémentaires sur l'émetteur ne seront pas nécessaires. Toutefois, l'intégrateur OEM est toujours responsable des essais sur son produit final pour toutes exigences de conformité supplémentaires requis pour ce module installé.

IMPORTANT NOTE:

In the event that these conditions can not be met (for example certain laptop configurations or co-location with another transmitter), then the Canada authorization is no longer considered valid and the IC ID can not be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate Canada authorization.

NOTE IMPORTANTE:

Dans le cas où ces conditions ne peuvent être satisfaites (par exemple pour certaines configurations d'ordinateur portable ou de certaines co-localisation avec un autre émetteur), l'autorisation du Canada n'est plus considéré comme valide et l'ID IC ne peut pas être utilisé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera chargé de réévaluer le produit final (y compris l'émetteur) et l'obtention d'une autorisation distincte au Canada.

End Product Labeling

The final end product must be labeled in a visible area with the following: "Contains IC:3147A-BL54L15".

Plaque signalétique du produit final

Le produit final doit être étiqueté dans un endroit visible avec l'inscription suivante: "Contient des IC: 3147A-BL54L15".

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

Manuel d'information à l'utilisateur final

L'intégrateur OEM doit être conscient de ne pas fournir des informations à l'utilisateur final quant à la façon d'installer ou de supprimer ce module RF dans le manuel de l'utilisateur du produit final qui intègre ce module.

Le manuel de l'utilisateur final doit inclure toutes les informations réglementaires requises et avertissements comme indiqué dans ce manuel.

This radio transmitter [IC: 3147A-BL54L15 has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Le présent émetteur radio [IC: 3147A-BL54L15] a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal. Les types d'antenne non inclus dans cette liste, et dont le gain est supérieur au gain maximal indiqué pour tout type figurant sur la liste, sont strictement interdits pour l'exploitation de l'émetteur.

12.3 Europe – EU Declaration of Conformity

This device complies with the essential requirements of the Radio Equipment directive: 2014 / 53 / EU. The following test methods have been applied in order to prove presumption of conformity with the essential requirements of the Radio Equipment directive: **2014 / 53 / EU**:

EN 300 328 V2.2.2
 (BS)EN 62497:2010
 (BS)EN 50663 2017
 EN 300 330 V2.1.1
 EN 301 489-1 V2.2.3
 EN 301 489-3 V2.3.2
 EN 301 489-17 V3.3.1
 IEC 62368-1:2018; and/or
 (BS) EN IEC 62368-1:2020+A11:2020

2400-2483.5GHz: **9.55dbm**
 BT LE: **9.58dbm**
 SW version: V0.5.6

RF exposure statement

The product comply with the RF exposure limit and is safe for intended operation as described in this manual. The further RF exposure reduction can be achieved if the product can be kept as far as possible from the user body.

12.4 Certified Antennas for the BL54L15/BL54L10

Table 8: Certified Antennas for BL54L15/BL54L10 Modules

Model	MPN	Manufacturer	Type	Connector	Peak Gain (2400 – 2500 MHz)
NanoBlue	EBL2400A1-10MH4L	Ezurio	PCB Dipole	IPEX MHF4	2 dBi
FlexPIFA	001-0022	Ezurio	FlexPIFA	IPEX MHF4L	2 dBi
EDA-8709-2G4C1-B27-CY	EDA-8709-2G4C1-B27-CY (Ezurio Part#0600-00057)	MAG.LAYERS	Dipole	IPEX MHF4	2.32 dBi
mFlexPIFA	EFA2400A3S-10MH4L	Ezurio	PIFA	IPEX MHF4L	2 dBi
I-FlexPIFATM Mini Series	EFG2401A3S-10MHF4L	Ezurio	I-FlexPIFA	IPEX MHF4L	2 dBi
Ezurio NFC	0600-00061	Ezurio	Coiled Inductor	FFC/FPC Connector	-

13 Bluetooth Qualification Process

13.1 Overview

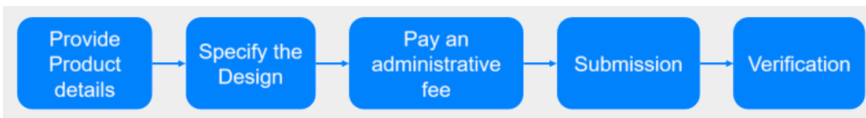
The Bluetooth Qualification Process promotes global product interoperability and reinforces the strength of the Bluetooth® brand and ecosystem to the benefit of all Bluetooth SIG members. The Bluetooth Qualification Process helps member companies ensure their products that incorporate Bluetooth technology comply with the Bluetooth Patent & Copyright License Agreement and the Bluetooth Trademark License Agreement (collectively, the Bluetooth License Agreement) and Bluetooth Specifications.

The Bluetooth Qualification Process is defined by the [Qualification Program Reference Document \(QPRD\) v3](#).

To demonstrate that a product complies with the Bluetooth Specification(s), each member must for each of its products:

- Identify the product, the design included in the product, the Bluetooth Specifications that the design implements, and the features of each implemented specification
- Complete the Bluetooth Qualification Process by submitting the required documentation for the product under a user account belonging to your company

The Bluetooth Qualification Process consists of the phases shown below:



To complete the Qualification Process the company developing a Bluetooth End Product shall be a member of the Bluetooth SIG. To start the application please use the following link: [Apply for Adopter Membership](#)

13.2 Scope

This guide is intended to provide guidance on the Bluetooth Qualification Process for End Products that reference a single existing design, that has not been modified, (refer to Section 3.2.1 of the [Qualification Program Reference Document v3](#)).

This option applies to a Member qualifying a Product that includes an existing Design that has a DN, QDID, or DID and that Design has not been modified (e.g., rebranding a Qualified Product from another Member). The Design identified by the DN, QDID, or DID may only implement Bluetooth Specifications that are active or deprecated at the time of Submission. No modifications may be made to the Design, including changes to the ICS Form.

Changes to the Product outside the Design are allowed, including:

- Enabling technologies
- Changes to the industrial design
- Changes to the communication technology other than Bluetooth
- Changes to the features that are unrelated to Bluetooth, branding, packaging, colour, shape, Product name, or Model number

Members are responsible for assessing that modifications to the Product outside of the Design do not affect compliance with Bluetooth Specifications or result in a change to the ICS Form.

For the purposes of this document, it is assumed that the member is combining a single unmodified Core-Complete Configuration.

13.3 Qualification Steps When Referencing a single existing design, (unmodified) – Option 1 in the QPRDv3

For this qualification, follow these steps:

1. To start a listing, go to: <https://qualification.bluetooth.com/>
2. Select **Start the Bluetooth Qualification Process**.
3. Product Details to be entered:
 - Project Name (this can be the product name or the Bluetooth Design name).
 - Product Description
 - Model Number
 - Product Publication Date (the product publication date may not be later than 90 days after submission)
 - Product Website (optional)
 - Internal Visibility (this will define if the product will be visible to other users prior to publication)
 - If you have multiple End Products to list then you can select 'Import Multiple Products', firstly downloading and completing the template, then by 'Upload Product List'. This will populate Qualification Workspace with all your products.
4. Specify the Design:
 - Do you include any existing Design(s) in your Product? Answer Yes, I do.

- Enter the single DN or QDID used in your, (for Option 1 only one DN or QDID can be referenced)
 - Once the DN or QDID is selected it will appear on the left-hand side, indicating the layers covered by the design.
 - Select 'I'm finished entering DN's
 - What do you want to do next? Answer, 'Use this Design without Modification'
 - Save and go to Product Qualification Fee
5. Product Qualification Fee:
- It's important to make sure a Prepaid Product Qualification fee is available as it is required at this stage to complete the Qualification Process.
 - Prepaid Product Qualification Fee's will appear in the available list so select one for the listing.
 - If one is not available select 'Pay Product Qualification Fee', payment can be done immediately via credit card, or you can pay via Invoice. Payment via credit will release the number immediately, if paying via invoice the number will not be released until the invoice is paid.
 - Once you have selected the Prepaid Qualification Fee, select 'Save and go to Submission'
6. Submission:
- Some automatic checks occur to ensure all submission requirements are complete.
 - To complete the listing any errors must be corrected
 - Once you have confirmed all design information is correct, tick all of the three check boxes and add your name to the signature page.
 - Now select 'Complete the Submission'.
 - You will be asked a final time to confirm you want to proceed with the submission, select 'Complete the Submission'.
 - Qualification Workspace will confirm the submission has been submitted. The Bluetooth SIG will email confirmation once the submission has been accepted, (normally this takes 1 working day).
7. Download Product and Design Details:
- a. You can now download a copy of the confirmed listing from the design listing page and save a copy in your Compliance Folder

For further information, please refer to the following webpage:

<https://www.bluetooth.com/develop-with-bluetooth/qualification-listing/>

13.4 Example Designs for reference

The following gives an example of a design possible under option 1:

Ezurio End Product design using Nordic Component based design

Design Name	Owner	Design ID	Link to listing on the SIG website
BL54L15/BL54L15µ	Ezurio	Q345095	https://qualification.bluetooth.com/ListingDetails/274104

13.5 Qualify More Products

If you develop further products based on the same design in the future, it is possible to add them free of charge. The new product must not modify the existing design i.e add ICS functionality, otherwise a new design listing will be required.

To add more products to your design, select 'Manage Submitted Products' in the **Getting Started** page, Actions, Qualify More Products. The tool will take you through the updating process.

14 Ordering Information

Part Number	Product Description
453-00001R	Module, BL54L15, (Nordic nRF54L15), Trace antenna, Tape/Reel
453-00044R	Module, BL54L15, (Nordic nRF54L15), MHF4 Connector, Tape/Reel
453-00001C	Module, BL54L15, (Nordic nRF54L15), Trace antenna, Cut Tape
453-00044C	Module, BL54L15, (Nordic nRF54L15), MHF4 Connector, Cut Tape
453-00001-K1	Development kit, Module, BL54L15 (Nordic nRF54L15), Trace antenna
453-00044-K1	Development kit, Module, BL54L15 (Nordic nRF54L15), MHF4 Connector
453-00225R	Module, BL54L10, (Nordic nRF54L10), Trace antenna, Tape/Reel
453-00226R	Module, BL54L10, (Nordic nRF54L10), MHF4 Connector, Tape/Reel
453-00225C	Module, BL54L10, (Nordic nRF54L10), Trace antenna, Cut Tape
453-00226C	Module, BL54L10, (Nordic nRF54L10), MHF4 Connector, Cut Tape



15 Additional Information

Please contact your local sales representative or our support team for further assistance:

Headquarters	Ezurio 50 S. Main St. Suite 1100 Akron, OH 44308 USA
Website	http://www.ezurio.com
Technical Support	http://www.ezurio.com/resources/support
Sales Contact	http://www.ezurio.com/contact

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